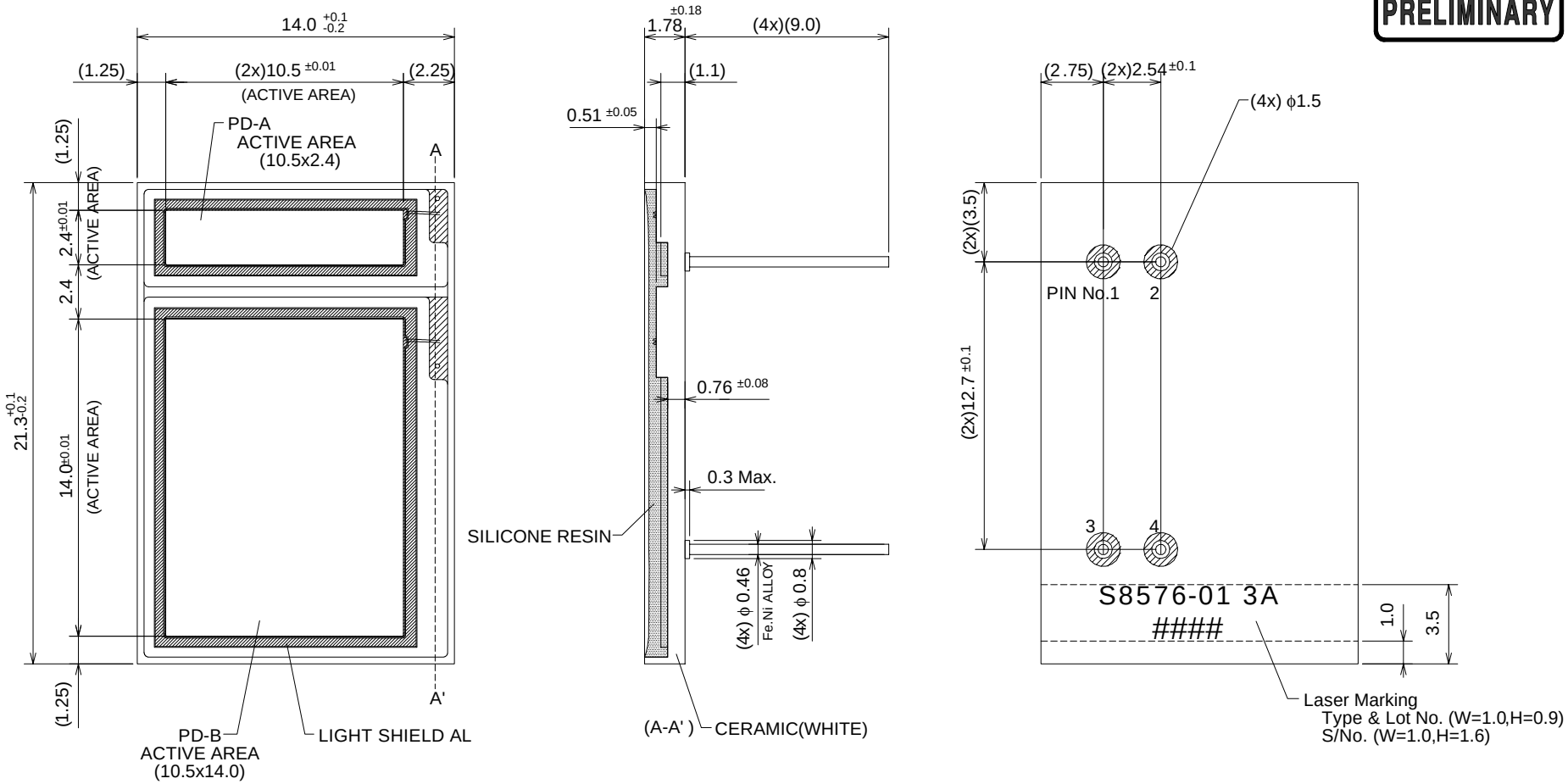
PRELIMINARY



PIN CONNECTION	
1	Cathode A
2	Anode A
3	Cathode B
4	Anode B

Note
The silicone resin shall not extend beyond the upper surface of the ceramic package.
The silicone resin shall cover the wires and the chips.
Leads finish : Gold and electroless Ni
The whole leads surface gold shall be removed and tinned by dipping into a solder (63% Sn, 37% Pb) bath held at 250-280 deg.C. for 2-3 seconds.
The clearance between the dies and the ceramic walls shall be 100µm Min.

GENERAL TOLERANCE : ±0.2

GLAST LAT CAL Dual PIN Photodiode □

LAT-DS-01237-01

MARK	CONTENTS	DATE	APPR	CHCK	CHCK	DESN	DRAW
c							
b							
a							
	FIRST ISSUE ...	2002.11.22					

UNIT	mm	SCALE	5/1	TITLE	S8576-01
PROJ				DWG.No	K03-F10893
REF				REV	

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